

ITW



Attorney Docket no: 0553-0193.01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayama et al.

Serial No.: 10/672,521

Filed: September 26, 2003

For: Wiring Material, Semiconductor Device  
Provided With A Wiring Using The Wiring  
Material And Method of Manufacturing  
Thereof

Examiner: Ha T. Nguyen

Art Unit: 2812

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

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Shannon Wallace

Name of applicant, assignee, or Registered Rep.  
Shannon Wallace 5/3/06  
Signature Date

**AMENDMENT E**

In response to the Office Action of February 3, 2006, please amend the above-identified  
application as follows: